



**DEFENSE LOGISTICS AGENCY**  
DEFENSE SUPPLY CENTER, COLUMBUS  
POST OFFICE BOX 3990  
COLUMBUS, OH 43218-3990

IN REPLY  
REFER TO

DSCC-VQ (VQC-06-010450/Mr. Tran/614-692-0606/dg)

May 02, 2006

SUBJECT: Laboratory Suitability for MIL-STD-883, FSC 5962

Marty Lanning  
President  
XTreme Semiconductor  
9000 Braesgate Cove  
Austin, TX 78717

Dear Mr. Lanning:

Xtreme Semiconductor has demonstrated to the Defense Supply Center, Columbus (DSCC) compliance with MIL-STD-883, the test standard for integrated circuits. Xtreme Semiconductor is granted laboratory suitability, effective March 29, 2006, for the facilities, test methods and conditions shown on the enclosure. All testing for Xtreme Semiconductor's products must be performed at these facilities and in accordance with MIL-PRF-38535 and MIL-STD-883 test methods.

This laboratory suitability is subject to the conditions in DoD 4120.24-M, Defense Standardization Program.

Xtreme Semiconductor shall notify the qualifying activity immediately after learning of a potential issuance of a GIDEP alert, problem advisory or major quality/reliability problem on their QPL/QML products utilizing these facilities and test methods listed on the enclosure. Failure to provide prior notification may be grounds for removal from QML-38535.

This laboratory suitability is valid until terminated by written notice from DSCC. If warranted, it may be withdrawn by DSCC at any time. Each of these facilities is subject to an audit by DSCC with a minimum notice.

Sincerely,

MICHAEL S. ADAMS  
Chief  
Custom Devices Team

Enclosure  
cc:  
VQC (Scott Thomas)

<b><u>TEST</u></b>	<b><u>METHOD/CONDITION</u></b>	<b>LOCATION 1</b>	<b>LOCATION 2</b>
<b>Moisture Resistance</b>	<b>1004</b>	<b>Golden Altos</b>	Maxwell
<b>Steady State Life Test</b>	<b>1005 / Condition A - E</b>	<b>Golden Altos</b>	Maxwell
<b>Stabilization Bake</b>	<b>1008 NA</b>	<b>Golden Altos</b>	Maxwell
<b>Salt Atmosphere</b>	<b>1009 / Condition A</b>	<b>Golden Altos</b>	Maxwell
<b>Temperature Cycling</b>	<b>1010 / Condition C</b>	<b>Golden Altos</b>	Maxwell
<b>Thermal Shock</b>	<b>1011 / Condition B</b>	<b>Golden Altos</b>	Maxwell
<b>Seal</b>	<b>1014 / Condition A or B, C</b>	<b>Golden Altos</b>	Maxwell
<b>Burn-in</b>	<b>1015 / Condition A - E</b>	<b>Golden Altos</b>	Maxwell
<b>Internal Water Vapor Content</b>	<b>1018</b>	<b>Golden Altos (using DSCC certified test lab for RGA)</b>	<b>Maxwell (using DSCC certified test lab for RGA)</b>
<b>Constant Acceleration</b>	<b>2001 / Condition C &amp; E</b>	<b>Golden Altos</b>	Maxwell
<b>Mechanical Shock</b>	<b>2002 / Condition B</b>	<b>Golden Altos</b>	Maxwell
<b>Solderability</b>	<b>2003</b>	<b>Golden Altos</b>	Maxwell
<b>Lead Integrity</b>	<b>2004 Condition B2 &amp; D</b>	<b>Golden Altos</b>	Maxwell
<b>Vibration, Variable Frequency</b>	<b>2007 Condition A</b>	<b>Golden Altos</b>	Maxwell
<b>External Visual</b>	<b>2009 Condition B</b>	<b>Golden Altos</b>	Maxwell
<b>Internal Visual</b>	<b>2010 Condition B</b>	<b>Golden Altos</b>	Maxwell
<b>Bond Strength</b>	<b>2011 Condition D</b>	<b>Golden Altos</b>	Maxwell
<b>Internal Visual &amp; Mechanical</b>	<b>2014 NA</b>	<b>Golden Altos</b>	Maxwell
<b>Resistance to Solvents</b>	<b>2015</b>	<b>Golden Altos</b>	Maxwell
<b>Physical Dimensions</b>	<b>2016</b>	<b>Golden Altos</b>	Maxwell
<b>SEM</b>	<b>2018 Used as Guide Line</b>	<b>Hi-Rel</b>	Maxwell
<b>Die Shear Strength</b>	<b>2019</b>	<b>Golden Altos</b>	Maxwell
<b>PIND</b>	<b>2020 / Condition A</b>	<b>Golden Altos</b>	Maxwell
<b>Glassivation Layer</b>	<b>2021</b>	<b>Golden Altos</b>	Maxwell
<b>Lid Torque</b>	<b>2024</b>	<b>Golden Altos</b>	Maxwell
<b>Adhesion of Lead Finish</b>	<b>2025</b>	<b>Golden Altos</b>	Maxwell
<b>Substrate Attach Strength</b>	<b>2027 NA</b>	<b>Golden Altos</b>	Maxwell
<b>ESDS Classification</b>	<b>3015 Human Body Model</b>	<b>Integra Technologies 1600 Wyatt Drive Suites 4,</b>	Maxwell

		<b>Santa Clara, CA 95054</b>	
<b>Electrical Test</b>	<b>Per MIL-STD-883 paragraph 4.5 and as specified in SMD</b>	<b>Anloy Technologies 1304 Wincrest Dr., Round Rock, TX 78664</b>	<b>Maxwell</b>
<b>Failure Analysis</b>	<b>SEM, &amp; Destructive Physical Analysis</b>	<b>Hi-Rel</b>	Maxwell